

(1.27 mm) .050"

HIGH-SPEED/HIGH-DENSITY OPEN-PIN-FIELD

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAM

- Insulator Material:** Black LCP
- Contact Material:** Copper Alloy
- Operating Temp Range:** -55 °C to +125 °C
- Current Rating (7 mm stack height):** 2.7 A per pin (10 adjacent pins powered)
- Plating:** Au or Sn over 50 μ" (1.27 μm) Ni
- Working Voltage:** 240 VAC
- RoHS Compliant:** Yes
- Lead-Free Solderable:** Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

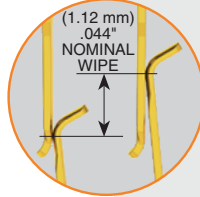


STANDARDS

- VITA 47
- VITA 57.1 FMC
- VITA 57.4 FMC+
- VITA 74 VNX
- PISMO™ 2

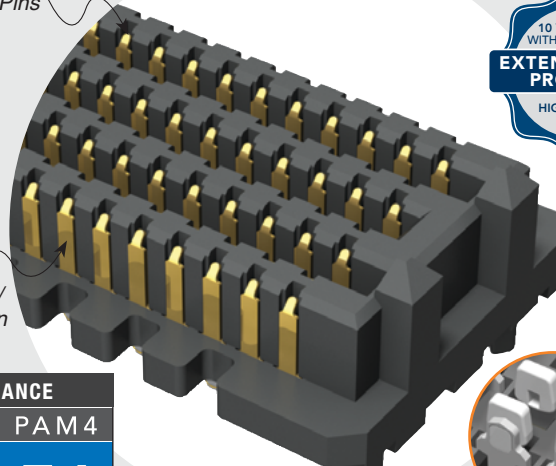
Visit www.samtec.com/standards for more information.

Mates with: SEAF, SEAFP
Standoffs: JSO



Up to 500 Pins

Low insertion/extraction forces



Solder charges

HIGH-SPEED CHANNEL PERFORMANCE

SEAF/SEAM @ 10 mm Mated Stack Height
Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com or contact SIG@samtec.com

PAM 4

56 Gbps

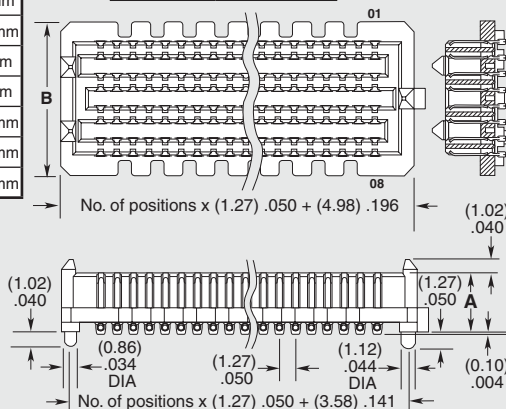
OTHER SOLUTIONS

- Up to 560 pins

SEAM	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	K	TR
		Specify LEAD STYLE from chart	<ul style="list-style-type: none"> -L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail -S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail 	<ul style="list-style-type: none"> -04 = Four Rows (-06.5 not available) -05 = Five Rows (-06.5 not available) -06 = Six Rows (-06.5 not available) -08 = Eight Rows -10 = Ten Rows 	<ul style="list-style-type: none"> -1 = Tin/Lead Alloy Solder Charge -2 = Lead-Free Solder Charge 	-A = Alignment Pins (Required. Arrays will not self-center on solder pads)	-K = Polyimide film Pick & Place Pad	-TR = Tape & Reel

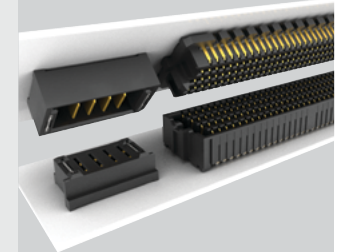
MATED HEIGHTS				
SEAM LEAD STYLE	SEAF LEAD STYLE			
	-05.0	-06.0	-06.5	-07.5
-02.0	7 mm	8 mm	8.5 mm	9.5 mm
-03.0	8 mm	9 mm	9.5 mm	10.5 mm
-03.5	8.5 mm	9.5 mm	10 mm	11 mm
-06.5	11.5 mm	12.5 mm	13 mm	14 mm
-07.0	12 mm	13 mm	13.5 mm	14.5 mm
-09.0	14 mm	15 mm	15.5 mm	16.5 mm
-11.0	16 mm	17 mm	17.5 mm	18.5 mm

NO. OF ROWS	B
-04	(7.06) .278
-05, -06	(9.60) .378
-08	(12.14) .478
-10	(14.68) .578



LEAD STYLE	A
-02.0	(4.60) .181
-03.0	(5.59) .220
-03.5	(6.10) .240
-06.5	(9.14) .360
-07.0	(9.60) .378
-09.0	(11.60) .457
-11.0	(13.60) .535

POWER/SIGNAL APPLICATION



Compatible with UMPT/UMPS for flexible two-piece power/signal solutions

Notes:

- Patented
- IPC-A-610F and IPC J-STD-001F Class 3 solder joint.
- Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.